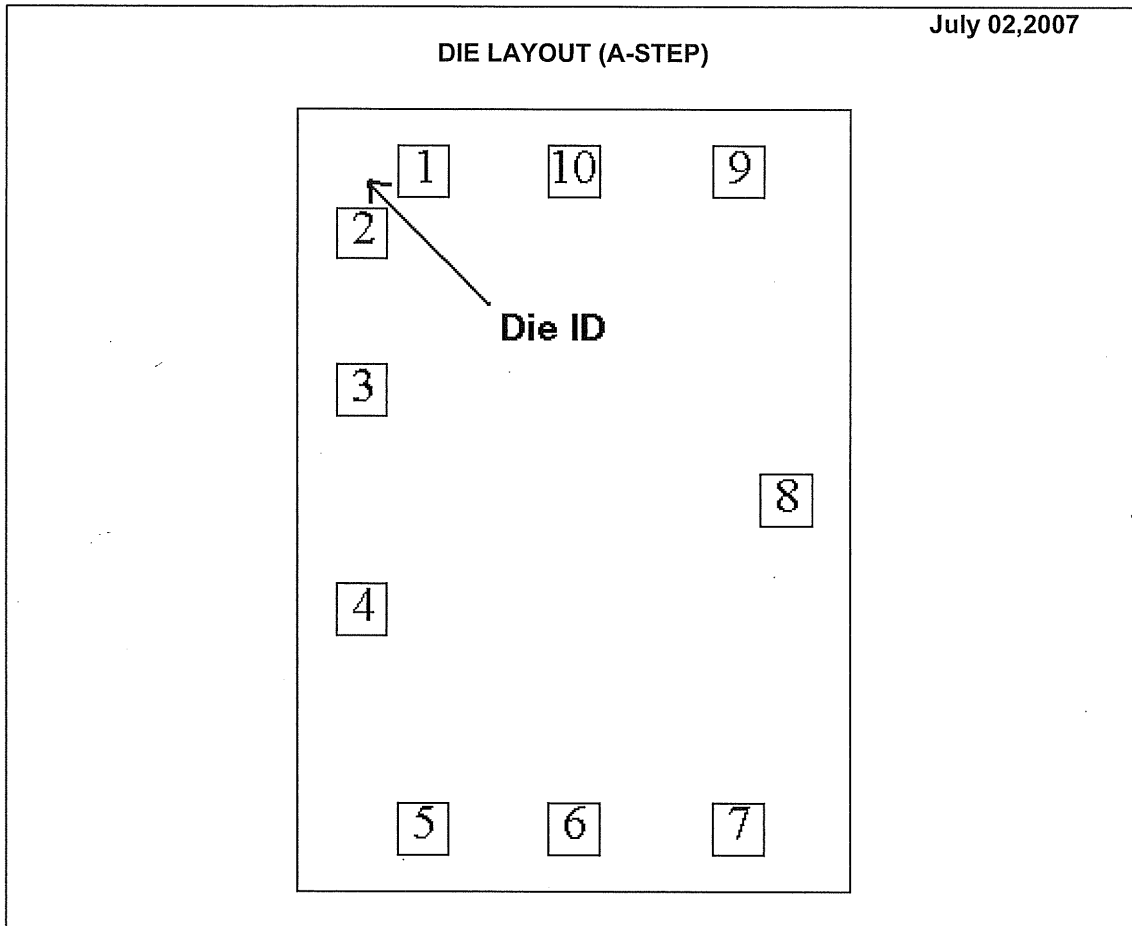


LMV794 MDA MWA
LOW NOISE AND LOW POWER AMPLIFIER



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LMV794A	Bond Pad Opening Size (min)	75 μ m x 75 μ m
Die Step	A	Bond Pad Metalization	Al_0.5%Cu
Physical Attributes		Passivation	PECVDOX+NITRIDE
Wafer Diameter	150mm	Back Side Metal	BARE BACK
Die Size (Drawn)	813 μ m x 1143 μ m 32.0mils x 45.0mils	Back Side Connection	Floating
Thickness	254 μ m Nominal		
Min Pitch	222.5 μ m Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (A -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	X/Y COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	Y
IN A+	1	-222	479	75	x	75
V-	2	-312	389	75	x	75
NC	3	-312	160	75	x	75
NC	4	-312	-160	75	x	75
IN B+	5	-222	-479	75	x	75
IN B -	6	0	-479	75	x	75
OUT B	7	243	-479	75	x	75
V+	8	312	0	75	x	75
OUT A	9	243	479	75	x	75
IN A-	10	0	479	75	x	75

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Notes

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